

4221430/B 06/2014

NOTES:

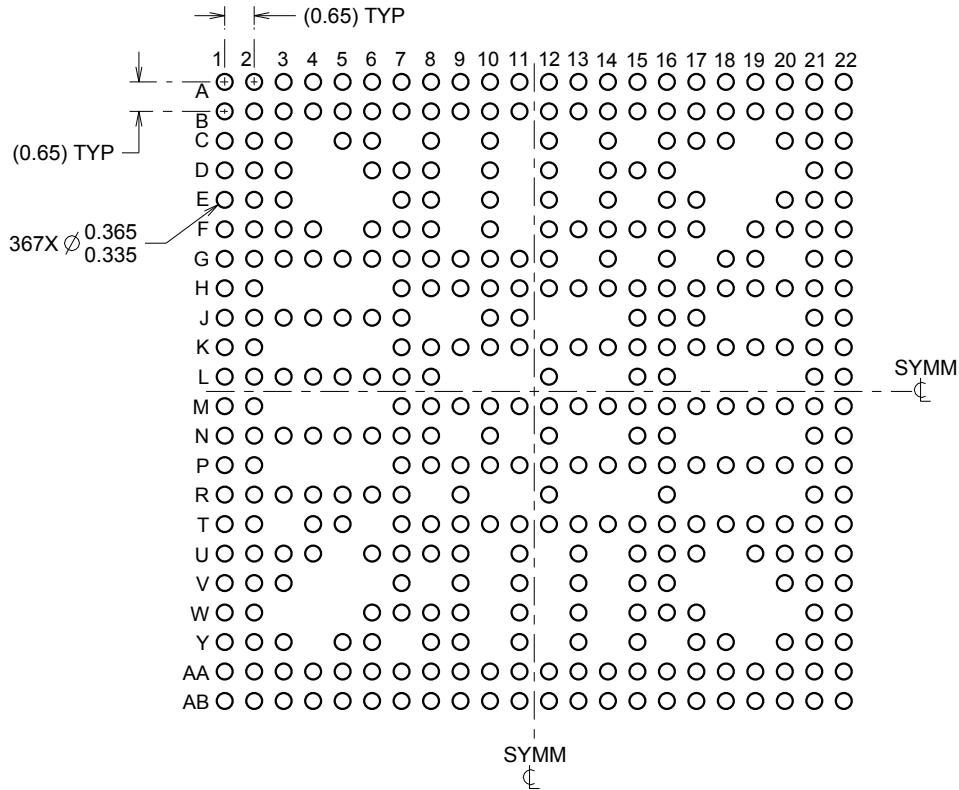
- All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
- This drawing is subject to change without notice.
- Dimension is measured at the maximum solder ball diameter, parallel to primary datum C.
- Primary datum C and seating plane are defined by the spherical crown of the solder balls.

EXAMPLE BOARD LAYOUT

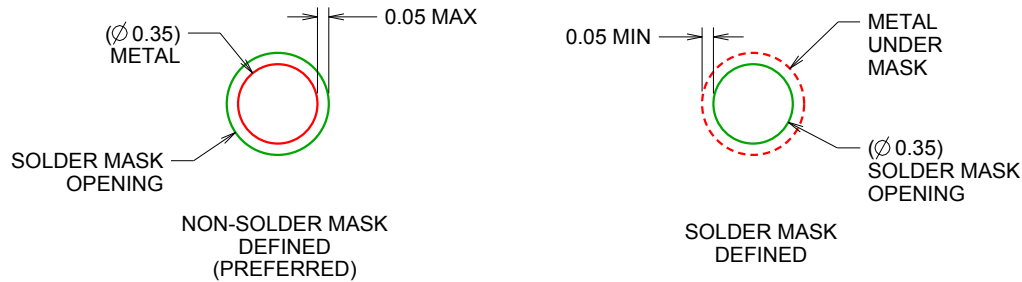
ABF0367A

FCBGA - 2.82 mm max height

BALL GRID ARRAY



LAND PATTERN EXAMPLE
SCALE:6X



SOLDER MASK DETAILS
NOT TO SCALE

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NOTES: (continued)

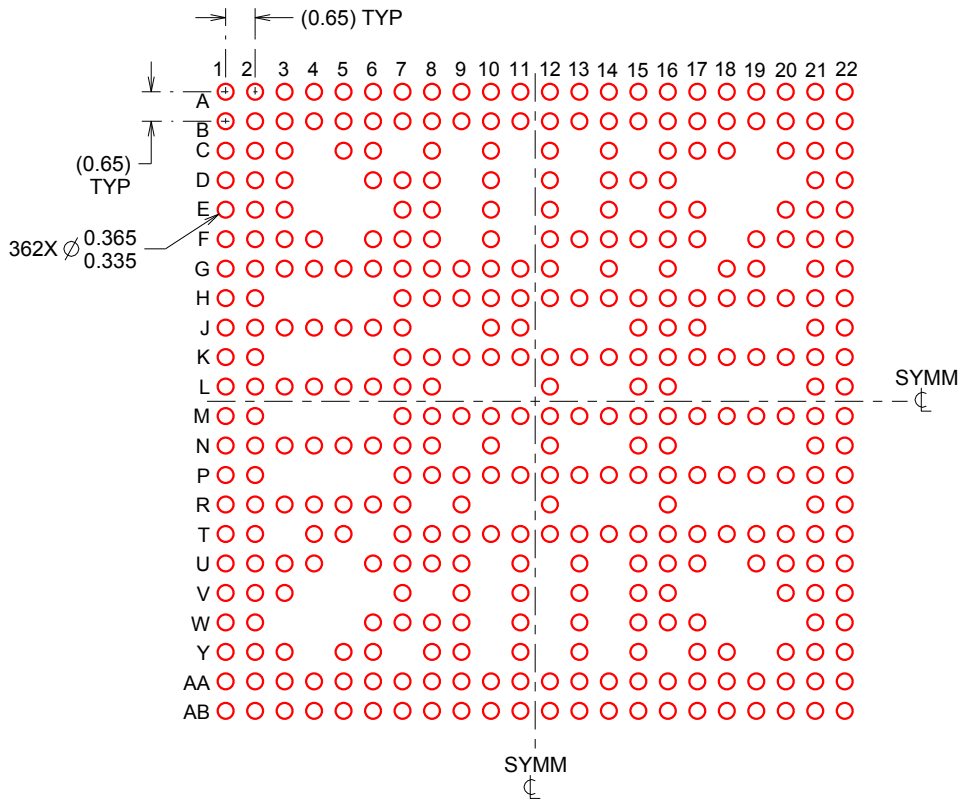
- Final dimensions may vary due to manufacturing tolerance considerations and also routing constraints. For more information, see Texas Instruments literature number SPRU811 (www.ti.com/lit/spru811).

EXAMPLE STENCIL DESIGN

ABF0367A

FCBGA - 2.82 mm max height

BALL GRID ARRAY



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:6X

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NOTES: (continued)

6. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release.

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